



0804MC

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8-Pin TO-3 Socket

FEATURES

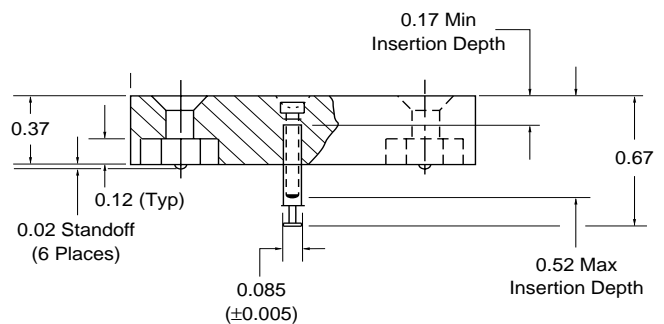
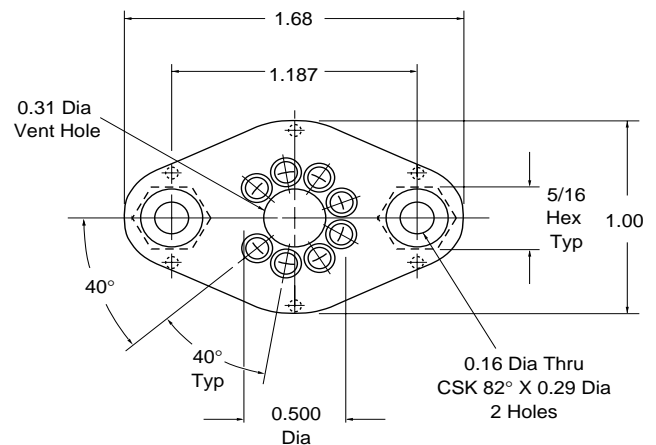
- LOW CONTACT RESISTANCE
- CLOSED CONTACT ENDS
- GOLD-PLATED INNER CONTACTS
- -55°C TO +150°C TEMPERATURE RANGE

DESCRIPTION

The 0804MC is a high quality socket designed for use with Burr-Brown's 8-pin TO-3 type products such as the OPA541 and OPA512.

Although not required for use with these products, the 0804MC socket makes interchanging parts easy, especially during design and testing. Its rugged inner contacts provide positive insertion and low contact resistance. Closed contact ends prevent solder and flux contamination of the internal contacts.

The socket body is molded of glass-filled polyester and incorporates counter-sunk mounting holes and hex-nut retaining feature. It accommodates a variety of mounting hardware and mechanical designs.



Contact Resistance: 0.02Ω Typ

Outer Contact: Brass
200μ inch Tin over 100μ inch Nickel Plate

Inner Contact: BeCu
30μ inch Gold over 50μ inch Nickel Plate

Socket Body: Glass-Filled Polyester, 94 V-0 rating

Operating Temperature Range: -55°C to +150°C

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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
0804MC	ACTIVE			0	55	TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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